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(Rev. 10/02)
OMB No. 0651-0027 (exp. 6/30/2005)

RECORDA



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Atty. Dkt. No.: BK-00003

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
**Kwang Seok Oh
Doo Hwan Moon**
Additional name(s) of conveying party(ies) attached?
 Yes No

2. Name and address of receiving party(ies):
Name: Amkor Technology, Inc.
Street Address: 1900 South Price Road
City/State/Zip: Chandler, AZ 85248-1604

22389 U.S. PTO
10702274



3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other

Additional name(s) & address(es) attached?
 Yes No

Execution Date: November 3, 2003

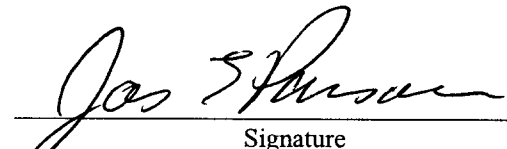
4. Application number(s) or patent number(s): **10702274**
If this document is being filed together with a new application, the execution date of the application is: November 5, 2003
A. Patent Application No.(s): B. Patent No.(s):

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name:
James E. Parsons, Esq.
Bever, Hoffman & Harms, LLP
2099 Gateway Place
Suite 320
San Jose, CA 95110

6. Total number of applications and patents involved: [1]
7. Total fee (37 CFR 3.41) \$40.00
 Enclosed
 Authorized to be charged to deposit account
8. Deposit account number: 50-0574
(Attorney Docket No.: BK-00003)

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9. Signature.
James E. Parsons  **November 5, 2003**
Name of Person Signing Signature Date
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PATENT
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ASSIGNMENT

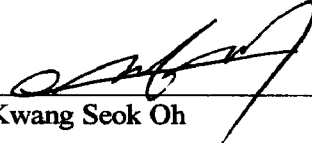
For good and valuable consideration, receipt of which is hereby acknowledged, we


Kwang Seok Oh of #201, 317-18 Jamsil-dong, Songpa-gu, Seoul, Republic of Korea
Doo Hwan Moon of #601-302, Hyundai APT 6, Guui-dong, Gwangjin-gu, Seoul, Republic of Korea

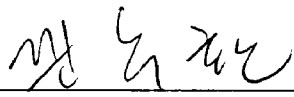
hereby sell, assign and transfer to **Amkor Technology, Inc.**, a Delaware corporation, having a place of business at 1900 South Price Road Chandler, AZ 85248-1604, its successors and assigns, the entire right, title and interest throughout the world in our invention in

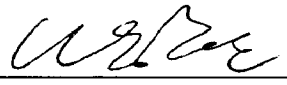
STACKABLE SEMICONDUCTOR PACKAGE AND MANUFACTURING METHOD THEREOF

for which we will execute a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 3 day of Nov., 2003. 
Kwang Seok Oh

Witness signature: 
Do Hyun Na

Executed this 3 day of Nov., 2003. 
Doo Hwan Moon

Witness signature: 
Do Hyun Na